

What is claimed is:

1. A method of encapsulating an article having first and second surfaces, comprising:
  - positioning the article on a carrier such that at least a portion of the first surface contacts the carrier;
  - positioning a portion of the carrier carrying the article within a mold;
  - forming a seal between the mold and the carrier; and
  - filling the mold with an encapsulating material in a manner that forms a seal between the article and the carrier.
2. The method of claim 1 wherein the positioning step includes positioning the article to prohibit the flow of any encapsulating material between the carrier and the first surface of the article.
3. The method of claim 2 further comprising underfilling the first surface of the article with an underfill material.
4. The method of claim 2 wherein the filling step forms a seal between the article and the carrier as a result of pressure exerted by the encapsulating material onto the second surface of the article as the encapsulating material fills the mold.
5. The method of claim 1 wherein the positioning step includes positioning the article to allow the flow of encapsulating material between a portion of the carrier and the first surface of the article.
6. The method of claim 5 wherein the filling step forms a seal between the article and the carrier as the pressure exerted by the encapsulating material onto the second surface of the article as the encapsulating material fills the mold exceeds the pressure exerted by the encapsulating material onto the first surface of the article.
7. The method of claim 1 wherein said carrier is comprised of polymeric core material overlaid with an adhesive material.

8. The method of claim 1 wherein said step of filling the molding section includes the step of filling the molding section with an encapsulating material chosen from a class consisting of epoxies, including thermo-set resins, silicones, sycar, polyimides, and polyurethanes.
9. The method of claim 8 including the step of curing the encapsulating material.
10. The method of claim 3 wherein the step of underfilling includes the step of underfilling the first surface of the article with an epoxy resin.
11. The method of claim 10 including the step of curing the epoxy resin.
12. The method of claim 1 wherein the carrier is further defined as having gaps such that at least a portion of the article positioned on the carrier is located on a gap.
13. A method of encapsulating an article having first and second surfaces, comprising:  
    positioning the article on a carrier such that at least a portion of the first surface contacts the carrier;  
    positioning a portion of the carrier carrying the article within a mold;  
    forming a seal between the mold and the carrier using clamping pressure; and  
    dynamically forming a seal between the article and the carrier by injecting an encapsulating material into the mold.
14. The method of claim 13 wherein the positioning step includes positioning the article to prohibit the flow of any encapsulating material between the carrier and the first surface of the article.
15. The method of claim 14 further comprising underfilling the first surface of the article with an underfill material.
16. The method of claim 15 wherein the dynamically forming a seal step results from the pressure exerted by the encapsulating material onto the second surface of the article as the encapsulating material fills the mold.

17. The method of claim 13 wherein the positioning step includes positioning the article to allow the flow of encapsulating material between the carrier and the first surface of the article.
18. The method of claim 17 wherein the dynamically forming a seal step results as the pressure exerted by the encapsulating material onto the second surface of the article as the encapsulating material fills the mold is greater than the pressure exerted by the encapsulating material onto the first surface of the article.
19. The method of claim 13 wherein said carrier is comprised of polymeric core material overlaid with an adhesive material.
20. The method of claim 13 wherein said step of dynamically forming a seal includes the step of injecting the molding section with an encapsulating material chosen from a class consisting of epoxies, including thermo-set resins, silicones, sycar, polyimides, and polyurethanes.
21. The method of claim 20 including the step of curing the encapsulating material.
22. The method of claim 15 wherein the step of underfilling includes the step of underfilling the first surface of the article with an epoxy resin.
23. The method of claim 22 including the step of curing the epoxy resin.
24. The method of claim 13 wherein the carrier is further defined as having gaps such that at least a portion of the article positioned on the carrier is located on a gap.
25. A sealing process for an article being encapsulated, comprising:  
    forming a first seal to prevent an encapsulating material from escaping from a mold with a clamping pressure; and  
    forming a second seal by exerting pressure on an article being encapsulated with the encapsulating material.

26. An overmolded die the size of a chip scale package and not having any substrate.

27. A chip scale packaged die having no substrate.

28. An overmolded die without a substrate, comprising:

a die having a first surface carrying electrical contacts; and

an encapsulation material sealing the die except for the electrical contacts.

29. The overmolded die of claim 28 wherein the encapsulated material is chosen from a class consisting of epoxies, including thermo-set resins, silicones, sycar, polyimides and polyurethanes.